

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## **SPECIFICATION**

(Reference sheet)

· Supplier : Samsung electro-mechanics · Samsung P/N : CL21B104KCFNNNE

Product : Multi-layer Ceramic Capacitor

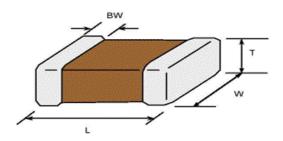
Description : CAP, 100nF, 100V, ±10%, X7R, 0805

#### A. Samsung Part Number

<u>CL</u> <u>21</u> <u>B</u> <u>104</u> <u>K</u> <u>C</u> <u>F</u> <u>N</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor				
② Size	0805 (inch code)	L: 2.00	± 0.10 mm	W: 1.25 ± 0.10 m	nm
3 Dielectric	X7R	8	Inner electrode	Ni	
Capacitance	100 nF		Termination	Cu	
⑤ Capacitance	±10 %		Plating	Sn 100%	(Pb Free)
tolerance		9	Product	Normal	
6 Rated Voltage	100 V	10	Special	Reserved for	future use
7 Thickness	1.25 ± 0.10 mm	111	Packaging	Embossed T	ype, 7" reel

#### **B. Structure & Dimension**



Samsung P/N	Dimension(mm)				
Samsung F/N	L	W	Т	BW	
CL21B104KCFNNNE	2.00 ± 0.10	1.25 ± 0.10	1.25 ± 0.10	0.50 +0.20/-0.30	

#### C. Samsung Reliablility Test and Judgement Condition

	Judgement	Test condition	
Capacitance	Within specified tolerance	1kHz ±10% / 1.0±0.2Vrms	
Tan δ (DF)	0.025 max.	*A capacitor prior to measuring the capacitance is heat treated at $150 ^{\circ}\text{C} + 0/-10 ^{\circ}\text{C}$ for 1hour and maintained in ambient air for $24 \pm 2$ hours.	
Insulation	10,000Mohm or 500Mohm× <i>µ</i> F	Rated Voltage 60±5 sec.	
Resistance	Whichever is smaller		
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding	No dielectric breakdown or	200% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	X7R		
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)		
Adhesive Strength	No peeling shall be occur on the	500g·f, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1 <sup>mm</sup> )	
		with 1.0mm/sec.	
Solderability	More than 95% of terminal surface	SnAg3.0Cu0.5 solder	
	is to be soldered newly	245±5°C, 3±0.3sec.	
		(preheating : 80~120°C for 10~30sec.)	
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5°C, 10±1sec.	
Soldering Heat	Tan δ, IR : initial spec.		
Vibration Test	Capacitance change : within ± 5%	Amplitude : 1.5mm	
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)	
		2hours × 3 direction (x, y, z)	
Moisture	Capacitance change : within ±12.5%	With rated voltage	
Resistance	Tan δ : 0.05 max	40±2°C, 90~95%RH, 500+12/-0hrs	
	IR : 500Mohm or 25Mohm × $\mu$ F		
	Whichever is smaller		
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage	
Resistance	Tan δ : 0.05 max	Max. operating temperature	
	IR : 1,000Mohm or 50Mohm × $\mu$ F	1,000+48/-0hrs	
	Whichever is smaller		
Temperature	Capacitance change : within ±7.5%	1 cycle condition	
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C	
		→ Max. operating temperature → 25°C	
		5 cycle test	

<sup>\*</sup> The reliability test condition can be replaced by the corresponding accelerated test condition.

#### D. Recommended Soldering method:

Reflow ( Reflow Peak Temperature : 250 °C, 6sec.max. )



Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

### - Disclaimer & Limitation of Use and Application -

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury.

We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- ① Aerospace/Aviation equipment
- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- Military equipment
- 5 Disaster prevention/crime prevention equipment
- Any other applications with the same as or similar complexity or reliability to the applications set forth above.